

**COMBINED DECLARATION/POWER OF ATTORNEY FOR UTILITY/DESIGN PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD OF SURFACE-MOUNTING SEMICONDUCTOR CHIP ON PCB

the specification of which is attached hereto, unless the following box is checked:

☐ was filed on \_\_\_ as United States Application Number or PCT International Application Number \_\_\_ and was amended on (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. § 1.56.

I hereby claim foreign priority benefit(s) under 35 U.S.C. ' 119(a)-(d) or ' 365(a)-(c) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application(s) for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

Priority NOT  
Claimed

<u>2003-49311</u>	<u>Republic of Korea</u>	<u>18 July 2003</u>	<input type="checkbox"/>
(Number)	(Country)	Day/Month/Year Filed	
(Number)	(Country)	Day/Month/Year Filed	<input type="checkbox"/>

I hereby claim the benefit under 35 U.S.C. ' 120 or ' 119(e) of any United States application(s), or ' 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application(s) in the manner provided by the first paragraph of 35 U.S.C. ' 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. ' 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

(Application Serial No.)

(Filing Date)

(Status -- patented, pending, abandoned)

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(Filing Date)

(Status -- patented, pending, abandoned)

I hereby appoint the attorneys and agents of Staas & Halsey LLP under USPTO Customer No. 21,171 to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:



21171  
PATENT TRADEMARK OFFICE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor Se-young JANG

Inventor's Signature [Signature] Date 2004/3/16

Residence Suwon city, Republic of Korea Citizenship Republic of Korea

Mailing Address 469-25, Pajang-dong, Changan-ku, Suwon city, Kyungki-do, Republic of Korea

Full name of second inventor Min-young PARK

Inventor's Signature [Signature] Date 2004/03/11

Residence Seongnam, city, Republic of Korea Citizenship Republic of Korea

Mailing Address Shinsung Apt. #307-1101, Soonae-dong, Boondang-ku, Seongnam city, Kyungki-do, Republic of Korea

Full name of third inventor Soon-min HONG

Inventor's Signature [Signature] Date 2004/03/11

Residence Seoul City, Republic of Korea Citizenship Republic of Korea

Mailing Address Shinhyundai Apt. #6-1503, Hoegi-dong, Seongdong-ku, Seoul City, Republic of Korea

☐ Additional inventors are being named on separately numbered sheets attached hereto.

신원 등록

## U.S. ASSIGNMENT

S&H 1100

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by

(Insert Name(s) & Address(es) of ASSIGNEE(S))

SAMSUNG ELECTRONICS CO., LTD.  
416, Maetan-dong, Yeongtong-gu  
Suwon-si, Gyeonggi-do  
Republic of Korea

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled  
(Title of Invention)

### METHOD OF SURFACE-MOUNTING SEMICONDUCTOR CHIP ON PCB

relating to International Patent Application PCT/JP\_\_\_\_\_/\_\_\_\_\_ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(a) executed on ;

(Insert date of execution of application, if not concurrent)

(b) filed on ,

Serial No. ;

Any registered attorney of STAAS & HALSEY LLP, 1201 New York Avenue, N.W., Suite 700 Washington, D.C. 20005 (202/434-1500) is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

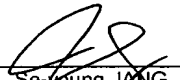
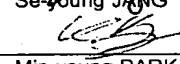
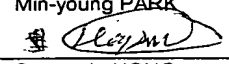
The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Typed Name & Signature of Inventor(s))

(Date)

(Typed Name & Signature of Witness(es))

1) ✓		2004/03/16	
	Se-young JANG		
2) ✓		2004/03/11	
	Min-young PARK		
3) ✓		2004/03/11	
	Soon-min HONG		
4)			
5)			
6)			
7)			

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